

# **11th "Trento" Workshop on Advanced Silicon Radiation Detectors**

Monday 22 February 2016 - Wednesday 24 February 2016

LPNHE

## **Book of Abstracts**



# Contents

3D Sensors for the HL-LHC 182 . . . . .	1
Beam test results of highly irradiated planar and 3D pixel sensors for the Phase II Upgrade of the CMS pixel detector 186 . . . . .	1
Beam test results of irradiated 3D pixel sensors for the CMS-TOTEM Precision Proton Spectrometer 175 . . . . .	1
Characterisation of thin irradiated epitaxial silicon sensors for the CMS phase II pixel upgrade 164 . . . . .	1
Charaterization of 3D module with micro-channel cooling 188 . . . . .	1
Charge Collection Properties of depleted Monolithic Active Pixel Sensors 151 . . . . .	1
Close-out 181 . . . . .	1
Comprehensive radiation damage test and modelling of p-type silicon detectors for high-luminosity operations 180 . . . . .	2
Detector development at the Paul-Scherrer-Institut (PSI) 156 . . . . .	2
Development of passive pixel sensors using a commercial 150nm CMOS technology on high resistivity silicon 152 . . . . .	2
Electric field, mobility and trapping in Si detectors irradiated with neutrons and protons up to $1e17 \text{ n}_{eq}/\text{cm}^2$ 146 . . . . .	2
First Inverted Low Gain Avalanche Detector fabrication at IMB-CNM 170 . . . . .	2
Initial results from a new generation of 3D Sensors for HL-LHC 174 . . . . .	2
Initial results from the electrical characterisation of planar p-on-n sensors with active/slim-edge for the next generation of FELs 168 . . . . .	3
Investigation on the radiation resistance of HV-CMOS and pin diodes using a Transient Current Technique based on the Two-Photon-Absorption Process 159 . . . . .	3
Latest development in HPK/KEK $n^+$ -in-p planar pixel sensors for very high radiation environments 165 . . . . .	3
Low Gain Avalanche Detectors TCAD Radiation Damage Analysis 169 . . . . .	3
Low Gain Avalanche Diode gallium process flow simulation studies 171 . . . . .	4

Monolithic CMOS ASIC Developments 153 . . . . .	4
New pixel technologies for HL-LHC 155 . . . . .	4
Performance of Edgeless Silicon Pixel Sensors on p-type substrate for the ATLAS High-Luminosity Upgrade 167 . . . . .	4
Pixel Sensor Development for the LHCb VELO Upgrade 161 . . . . .	4
Practical information 189 . . . . .	5
Progress in Ultra-Fast Silicon Detectors 144 . . . . .	5
Recent results with hybrid pixel assemblies for the CLIC vertex detector 147 . . . . .	5
Results on thin n in p Planar Pixels from INFN R&D 163 . . . . .	5
Reverse bias current characterisation of silicon strip sensors and shallow radiation damage generation 157 . . . . .	5
SPS Test Beam characterisation results with CCPDv4 capacitively coupled to FEI4 160 . . . . .	5
Silicon pixel tracking detector with ultra-precise time resolution 148 . . . . .	6
Status of 3D detector activities at CNM 173 . . . . .	6
Status of LGAD CNM fabrications 172 . . . . .	6
Study of New ADVACAM Active Edge Sensor Technology for ATLAS Upgrade 166 . . . . .	6
TCAD simulations of High-Voltage-CMOS pixel structures for the CLIC vertex detector 177 . . . . .	6
TCAD simulations of LGAD devices using Silvaco software 179 . . . . .	6
TCT measurements of HV-CMOS test structures irradiated with neutrons 158 . . . . .	6
The Belle II SVD Origami Modules 150 . . . . .	7
The Phase 1 upgrade of the CMS pixel detector 162 . . . . .	7
The first reticle size HV-CMOS sensor demonstrator for ATLAS pixel layers 187 . . . . .	7
The impact and persistence of static surface charges on differently passivated silicon strip sensors 154 . . . . .	7
The upgraded ATLAS Pixel detector and its performance during run-2 in 2015 184 . . . . .	7
Tracking in 4 dimensions 145 . . . . .	7
Validation strategy for the simulation of highly irradiated silicon pixel sensors 178 . . . . .	8
Welcome 143 . . . . .	8
X-rays characterisation of pixelated silicon detectors 149 . . . . .	8

**Introduction / 182**

## **3D Sensors for the HL-LHC**

**Corresponding Author(s):** sgrinstein@ifae.es

**Planar 1 / 186**

## **Beam test results of highly irradiated planar and 3D pixel sensors for the Phase II Upgrade of the CMS pixel detector**

**Corresponding Author(s):** daniel.schell@cern.ch

**3D / 175**

## **Beam test results of irradiated 3D pixel sensors for the CMS-TOTEM Precision Proton Spectrometer**

**Corresponding Author(s):** fabio.ravera@cern.ch

**Planar 2 / 164**

## **Characterisation of thin irradiated epitaxial silicon sensors for the CMS phase II pixel upgrade**

**Corresponding Author(s):** matteo.centis.vignali@cern.ch

**3D / 188**

## **Charaterization of 3D module with micro-channel cooling**

**Corresponding Author(s):** cinzia.da.via@cern.ch

**HVCMOS 1 / 151**

## **Charge Collection Properties of depleted Monolithic Active Pixel Sensors**

**Corresponding Author(s):** malte.backhaus@cern.ch

**Conference closing / 181**

## **Close-out**

TCAD / 180

### **Comprehensive radiation damage test and modelling of p-type silicon detectors for high-luminosity operations**

Corresponding Author(s): arianna.morozzi@gmail.com

Technology / 156

### **Detector development at the Paul-Scherrer-Institut (PSI)**

Corresponding Author(s): dominic.greiffenberg@psi.ch

HVCMOS 1 / 152

### **Development of passive pixel sensors using a commercial 150nm CMOS technology on high resistivity silicon**

Corresponding Author(s): fabian.huegging@cern.ch, huegging@physik.uni-bonn.de

Introduction / 146

### **Electric field, mobility and trapping in Si detectors irradiated with neutrons and protons up to $1e17 \text{ n}_{\text{eq}}/\text{cm}^2$**

Corresponding Author(s): marko.mikuz@cern.ch

LGAD / 170

### **First Inverted Low Gain Avalanche Detector fabrication at IMB-CNM**

Corresponding Author(s): mar.carulla@imb-cnm.csic.es

3D / 174

### **Initial results from a new generation of 3D Sensors for HL-LHC**

Corresponding Author(s): boscardi@fbk.eu, maurizio.boscardin@cern.ch

Planar 3 / 168

## Initial results from the electrical characterisation of planar p-on-n sensors with active/slim-edge for the next generation of FELs

Corresponding Author(s): gianfranco.dallabetta@unitn.it, gian.franco.dalla.betta@cern.ch

HVCMOS 2 / 159

## Investigation on the radiation resistance of HV-CMOS and pin diodes using a Transient Current Technique based on the Two-Photon-Absorption Process

Author(s): Ivan Vila Alvarez<sup>1</sup>

Co-author(s): David Moya Martin <sup>1</sup> ; Francisco Rogelio Palomo Pinto <sup>1</sup> ; Gregor Kramberger <sup>2</sup> ; Javier Gonzalez Sanchez <sup>1</sup> ; Marcos Fernandez Garcia <sup>1</sup> ; Michael Moll <sup>3</sup> ; Richard Jaramillo <sup>4</sup> ; Salvador Hidalgo Villena <sup>5</sup>

<sup>1</sup> Universidad de Cantabria (ES)

<sup>2</sup> Jozef Stefan Institute (SI)

<sup>3</sup> CERN

<sup>4</sup> IFCA

<sup>5</sup> Instituto de Microelectronica de Barcelona (ES)

Corresponding Author(s): ivan.vila@cern.ch, marcos.fernandez@cern.ch, francisco.rogelio.palomo.pinto@cern.ch, michael.moll@cern.ch, jaramillo@ifca.unican.es, javier.gonzalez.sanchez@cern.ch, gregor.kramberger@ijs.si, hidalgo.salvador@cern.ch, david.moya.martin@cern.ch

Transient Current Techniques (TCT) based on laser-induced photo-currents produced by Single Photon Absorption (SPA) processes have been extensively used during the last two decades as a powerful tool to study many of the properties relevant to operation of semiconductor detectors.

Very recently, an innovative Transient Current Technique was introduced where the free charge carriers are created in a Two-Photon-Absorption (TPA) process induced by a focused femto-second laser pulse with a wavelength of 1300nm. The fact that in a TPA process the absorption of the light depends on the square of the intensity of the light beam used for the current generation allows a localized TPA-induced electron-hole pair creation in a micrometric scale voxel centered on the laser waist. As a consequence, this new technique opens the possibility to carry out a 3D mapping of the sensor's space-charge properties with micrometric resolution.

Due to its intrinsic spatial resolution, the TPA-TCT technique should be a very appropriate choice for the characterization of the alterations of the sensor's active (charge collecting) volume induced by radiation damage and especially for the case of partially depleted sensors as it is the case of the carrier collecting n-well implemented in HV-CMOS sensors.

Planar 3 / 165

## Latest development in HPK/KEK n<sup>+</sup>-in-p planar pixel sensors for very high radiation environments

Corresponding Author(s): yoshinobu.unno@kek.jp

LGAD / 169

## Low Gain Avalanche Detectors TCAD Radiation Damage Analysis

**Co-author(s):** Ivan Vila Alvarez <sup>1</sup> ; Salvador Hidalgo Villena <sup>2</sup>

<sup>1</sup> *Universidad de Cantabria (ES)*

<sup>2</sup> *Instituto de Microelectronica de Barcelona (ES)*

**Corresponding Author(s):** francisco.rogelio.palomo.pinto@cern.ch, rpalomop@cern.ch, ivan.vila@cern.ch, hidalgo.salvador@cern.ch

Where we present our last results on radiation damage analysis of Low Gain Avalanche Detectors using the Synopsys TCAD suite and different well established radiation damage models. Our main conclusions point to this device could work reasonably well up to  $\sim 1e14$  n\_eq/cm<sup>2</sup>.

LGAD / 171

## Low Gain Avalanche Diode gallium process flow simulation studies

**Corresponding Author(s):** evangelos.-gkougkousis@cern.ch, vagelis.gkougkousis@cern.ch

HVCMOS 1 / 153

## Monolithic CMOS ASIC Developments

**Corresponding Author(s):** pietroc@slac.stanford.edu

Technology / 155

## New pixel technologies for HL-LHC

**Corresponding Author(s):** andrea.gaudiello@cern.ch

Planar 3 / 167

## Performance of Edgeless Silicon Pixel Sensors on p-type substrate for the ATLAS High-Luminosity Upgrade

**Corresponding Author(s):** audrey.ducourthial@cern.ch

Planar 2 / 161



## **Pixel Sensor Development for the LHCb VELO Upgrade**

**Corresponding Author(s):** asmund.schiager.folkestad@cern.ch, asmund\_sf@hotmail.com

**Introduction / 189**

## **Practical information**

**Corresponding Author(s):** marco.bomben@cern.ch, giovanni.marchiori@cern.ch

**Introduction / 144**

## **Progress in Ultra-Fast Silicon Detectors**

**Corresponding Author(s):** hartmut@scipp.ucsc.edu, hartmut@ucsc.edu

**Planar 1 / 147**

## **Recent results with hybrid pixel assemblies for the CLIC vertex detector**

**Corresponding Author(s):** andreas.nurnberg@cern.ch, andreas.matthias.nurnberg@cern.ch

**Planar 2 / 163**

## **Results on thin n in p Planar Pixels from INFN R&D**

**Corresponding Author(s):** marco.meschini@cern.ch

**Technology / 157**

## **Reverse bias current characterisation of silicon strip sensors and shallow radiation damage generation**

**Corresponding Author(s):** sven.wonsak@cern.ch

**HVCMOS 2 / 160**

## **SPS Test Beam characterisation results with CCPDv4 capacitively coupled to FEI4**

**Corresponding Author(s):** francesco.armando.di.bello@cern.ch

Planar 1 / 148

## **Silicon pixel tracking detector with ultra-precise time resolution**

Corresponding Author(s): [massimiliano.fiorini@cern.ch](mailto:massimiliano.fiorini@cern.ch)

3D / 173

## **Status of 3D detector activities at CNM**

Corresponding Author(s): [giulio.pellegrini@cnm.es](mailto:giulio.pellegrini@cnm.es), [giulio.pellegrini@csic.es](mailto:giulio.pellegrini@csic.es)

LGAD / 172

## **Status of LGAD CNM fabrications**

Corresponding Author(s): [giulio.pellegrini@cnm.es](mailto:giulio.pellegrini@cnm.es), [giulio.pellegrini@csic.es](mailto:giulio.pellegrini@csic.es)

Planar 3 / 166

## **Study of New ADVACAM Active Edge Sensor Technology for ATLAS Upgrade**

Corresponding Author(s): [tasneem.rashid@cern.ch](mailto:tasneem.rashid@cern.ch)

TCAD / 177

## **TCAD simulations of High-Voltage-CMOS pixel structures for the CLIC vertex detector**

Corresponding Author(s): [matthew.daniel.buckland@cern.ch](mailto:matthew.daniel.buckland@cern.ch)

TCAD / 179

## **TCAD simulations of LGAD devices using Silvaco software**

Corresponding Author(s): [marco.bomben@cern.ch](mailto:marco.bomben@cern.ch)

HVCMOS 2 / 158

## **TCT measurements of HV-CMOS test structures irradiated with neutrons**

Corresponding Author(s): igor.mandic@ijs.si

Planar 1 / 150

## **The Belle II SVD Origami Modules**

Corresponding Author(s): antonio.paladino@pi.infn.it

Planar 2 / 162

## **The Phase 1 upgrade of the CMS pixel detector**

Corresponding Author(s): viktor.veszpremi@cern.ch

HVCMOS 1 / 187

## **The first reticle size HV-CMOS sensor demonstrator for ATLAS pixel layers**

Corresponding Author(s): ivan.peric@kit.edu

Technology / 154

## **The impact and persistence of static surface charges on differently passivated silicon strip sensors**

Corresponding Author(s): axel.koenig@oeaw.ac.at

Planar 2 / 184

## **The upgraded ATLAS Pixel detector and its performance during run-2 in 2015**

Corresponding Author(s): didier.ferrere@cern.ch

Introduction / 145

## **Tracking in 4 dimensions**

**Corresponding Author(s):** cartiglia@to.infn.it, nicolo.cartiglia@cern.ch

**TCAD / 178**

## **Validation strategy for the simulation of highly irradiated silicon pixel sensors**

**Corresponding Author(s):** joern.schwandt@cern.ch

**Introduction / 143**

## **Welcome**

**Corresponding Author(s):** giovanni.calderini@cern.ch

**Planar 1 / 149**

## **X-rays characterisation of pixelated silicon detectors**

**Corresponding Author(s):** dima.maneuski@glasgow.ac.uk, dzmitry.maneuski@cern.ch